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FAIRCHILD SEMICONDUCTOR™

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# MM74HC02
# Quad 2-Input NOR Gate

## General Description

The MM74HC02 NOR gates utilize advanced silicon-gate CMOS technology to achieve operating speeds similar to LS-TTL gates with the low power consumption of standard CMOS integrated circuits. All gates have buffered outputs, providing high noise immunity and the ability to drive 10 LS-TTL loads. The 74HC logic family is functionally as well as pin-out compatible with the standard 74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to $V_{CC}$ and ground.

## Features

- Typical propagation delay: 8 ns
- Wide power supply range: 2–6V
- Low quiescent supply current: 20 µA maximum (74HC Series)
- Low input current: 1 µA maximum
- High output current: 4 mA minimum

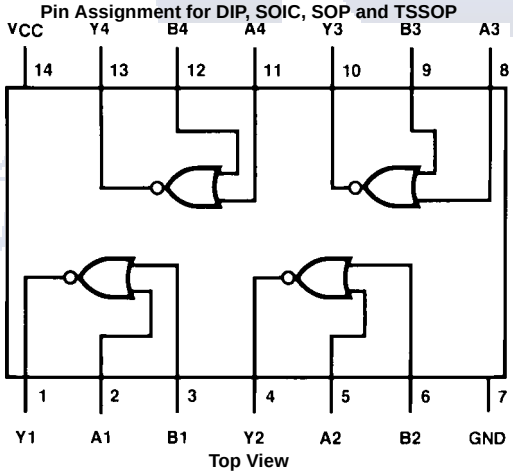
## Ordering Code:

| Order Number | Package Number | Package Description |
|---|---|---|
| MM74HC02M | M14A | 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-120, 0.150" Narrow Body |
| MM74HC02SJ | M14D | 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide |
| MM74HC02MTC | MTC14 | 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide |
| MM74HC02N | N14A | 14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide |

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code. (Tape and Reel not available in N14A.)

## Connection Diagram

Pin Assignment for DIP, SOIC, SOP and TSSOP




Top View

## Logic Diagram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## Absolute Maximum Ratings (Note 1)

(Note 2)

| | |
|---|---|
| Supply Voltage ($V_{CC}$) | −0.5 to +7.0V |
| DC Input Voltage ($V_{IN}$) | −1.5 to $V_{CC}$ +1.5V |
| DC Output Voltage ($V_{OUT}$) | −0.5 to $V_{CC}$ +0.5V |
| Clamp Diode Current ($I_{IK}$, $I_{OK}$) | ±20 mA |
| DC Output Current, per pin ($I_{OUT}$) | ±25 mA |
| DC $V_{CC}$ or GND Current, per pin ($I_{CC}$) | ±50 mA |
| Storage Temperature Range ($T_{STG}$) | −65°C to +150°C |
| Power Dissipation ($P_D$) | |
| (Note 3) | 600 mW |
| S.O. Package only | 500 mW |
| Lead Temperature ($T_L$) | |
| (Soldering 10 seconds) | 260°C |

## Recommended Operating Conditions

| | Min | Max | Units |
|---|---|---|---|
| Supply Voltage ($V_{CC}$) | 2 | 6 | V |
| DC Input or Output Voltage ($V_{IN}$, $V_{OUT}$) | 0 | $V_{CC}$ | V |
| Operating Temperature Range ($T_A$) | −40 | +125 | °C |
| Input Rise or Fall Times | | | |
| ($t_r$, $t_f$) $V_{CC}$ = 2.0V | | 1000 | ns |
| $V_{CC}$ = 4.5V | | 500 | ns |
| $V_{CC}$ = 6.0V | | 400 | ns |

**Note 1:** Absolute Maximum Ratings are those values beyond which damage to the device may occur.

**Note 2:** Unless otherwise specified all voltages are referenced to ground.

**Note 3:** Power Dissipation temperature derating — plastic "N" package: −12 mW/°C from 65°C to 85°C.

## DC Electrical Characteristics (Note 4)

| Symbol | Parameter | Conditions | $V_{CC}$ | $T_A$ = 25°C | $T_A$ = −40 to 85°C | $T_A$ = −40 to 125°C | Units |
|---|---|---|---|---|---|---|---|
| | | | | Typ | Guaranteed Limits | | |
| $V_{IH}$ | Minimum HIGH Level Input Voltage | | 2.0V | | 1.5 | 1.5 | 1.5 | V |
| | | | 4.5V | | 3.15 | 3.15 | 3.15 | V |
| | | | 6.0V | | 4.2 | 4.2 | 4.2 | V |
| $V_{IL}$ | Maximum LOW Level Input Voltage | | 2.0V | | 0.5 | 0.5 | 0.5 | V |
| | | | 4.5V | | 1.35 | 1.35 | 1.35 | V |
| | | | 6.0V | | 1.8 | 1.8 | 1.8 | V |
| $V_{OH}$ | Minimum HIGH Level Output Voltage | $V_{IN}$ = $V_{IL}$ | | | | | | |
| | | $\|I_{OUT}\|$ ≤ 20 μA | 2.0V | 2.0 | 1.9 | 1.9 | 1.9 | V |
| | | | 4.5V | 4.5 | 4.4 | 4.4 | 4.4 | V |
| | | | 6.0V | 6.0 | 5.9 | 5.9 | 5.9 | V |
| | | $V_{IN}$ = $V_{IL}$ | | | | | | |
| | | $\|I_{OUT}\|$ ≤ 4.0 mA | 4.5V | 4.2 | 3.98 | 3.84 | 3.7 | V |
| | | $\|I_{OUT}\|$ ≤ 5.2 mA | 6.0V | 5.7 | 5.48 | 5.34 | 5.2 | V |
| $V_{OL}$ | Maximum LOW Level Output Voltage | $V_{IN}$ = $V_{IH}$ or $V_{IL}$ | | | | | | |
| | | $\|I_{OUT}\|$ ≤ 20 μA | 2.0V | 0 | 0.1 | 0.1 | 0.1 | V |
| | | | 4.5V | 0 | 0.1 | 0.1 | 0.1 | V |
| | | | 6.0V | 0 | 0.1 | 0.1 | 0.1 | V |
| | | $V_{IN}$ = $V_{IH}$ or $V_{IL}$ | | | | | | |
| | | $\|I_{OUT}\|$ ≤ 4.0 mA | 4.5V | 0.2 | 0.26 | 0.33 | 0.4 | V |
| | | $\|I_{OUT}\|$ ≤ 5.2 mA | 6.0V | 0.2 | 0.26 | 0.33 | 0.4 | V |
| $I_{IN}$ | Maximum Input Current | $V_{IN}$ = $V_{CC}$ or GND | 6.0V | | ±0.1 | ±1.0 | ±1.0 | μA |
| $I_{CC}$ | Maximum Quiescent Supply Current | $V_{IN}$ = $V_{CC}$ or GND | 6.0V | | 2.0 | 20 | 40 | μA |
| | | $I_{OUT}$ = 0 μA | | | | | | |

**Note 4:** For a power supply of 5V ±10% the worst case output voltages ($V_{OH}$, and $V_{OL}$) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case $V_{IH}$ and $V_{IL}$ occur at $V_{CC}$=5.5V and 4.5V respectively. (The $V_{IH}$ value at 5.5V is 3.85V.) The worst case leakage current ($I_{IN}$, $I_{CC}$, and $I_{OZ}$) occur for CMOS at the higher voltage and so the 6.0V values should be used.





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## AC Electrical Characteristics

$V_{CC}$ = 5V, $T_A$ = 25°C, $C_L$ = 15 pF, $t_r$ = $t_f$ = 6 ns

| Symbol | Parameter | Conditions | Typ | Guaranteed Limit | Units |
|---|---|---|---|---|---|
| $t_{PHL}$, $t_{PLH}$ | Maximum Propagation Delay | | 8 | 15 | ns |

## AC Electrical Characteristics

$V_{CC}$ = 2.0V to 6.0V, $C_L$ = 50 pF, $t_r$ = $t_f$ = 6 ns (unless otherwise specified)

| Symbol | Parameter | Conditions | $V_{CC}$ | $T_A$ = 25°C | $T_A$ = −40 to 85°C | $T_A$ = −55 to 125°C | Units |
|---|---|---|---|---|---|---|---|
| | | | | Typ | Guaranteed Limits | | |
| $t_{PHL}$, $t_{PLH}$ | Maximum Propagation Delay | | 2.0V | 45 | 90 | 113 | 134 | ns |
| | | | 4.5V | 9 | 18 | 23 | 27 | ns |
| | | | 6.0V | 8 | 15 | 19 | 23 | ns |
| $t_{TLH}$, $t_{THL}$ | Maximum Output Rise and Fall Time | | 2.0V | 30 | 75 | 95 | 110 | ns |
| | | | 4.5V | 8 | 15 | 19 | 22 | ns |
| | | | 6.0V | 7 | 13 | 16 | 19 | ns |
| $C_{PD}$ | Power Dissipation Capacitance (Note 5) | (per gate) | | 20 | | | | pF |
| $C_{IN}$ | Maximum Input Capacitance | | | 5 | 10 | 10 | 10 | pF |

**Note 5:** $C_{PD}$ determines the no load dynamic power consumption, $P_D = C_{PD}\ V_{CC}^2\ f + I_{CC}\ V_{CC}$, and the no load dynamic current consumption, $I_S = C_{PD}\ V_{CC}\ f + I_{CC}$.






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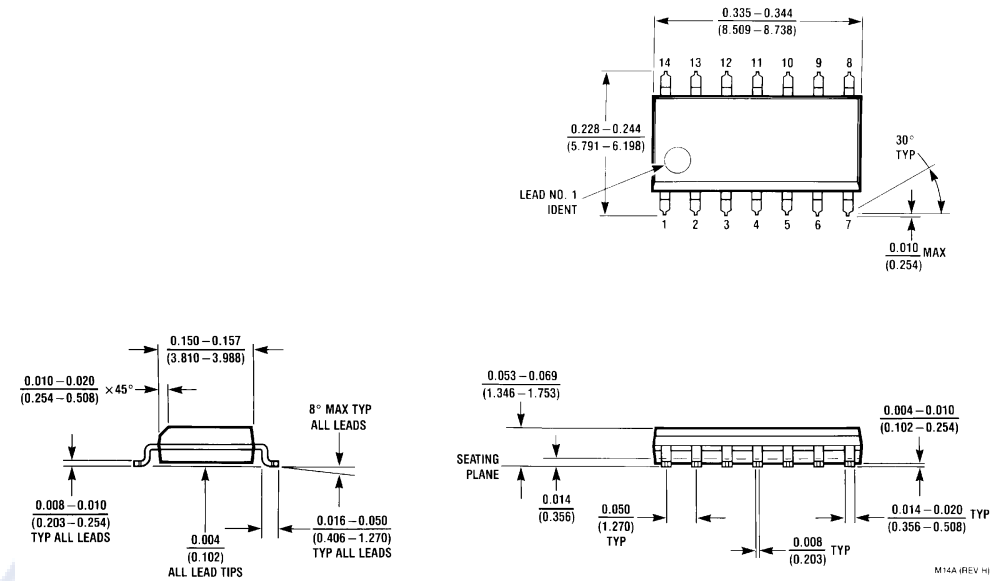
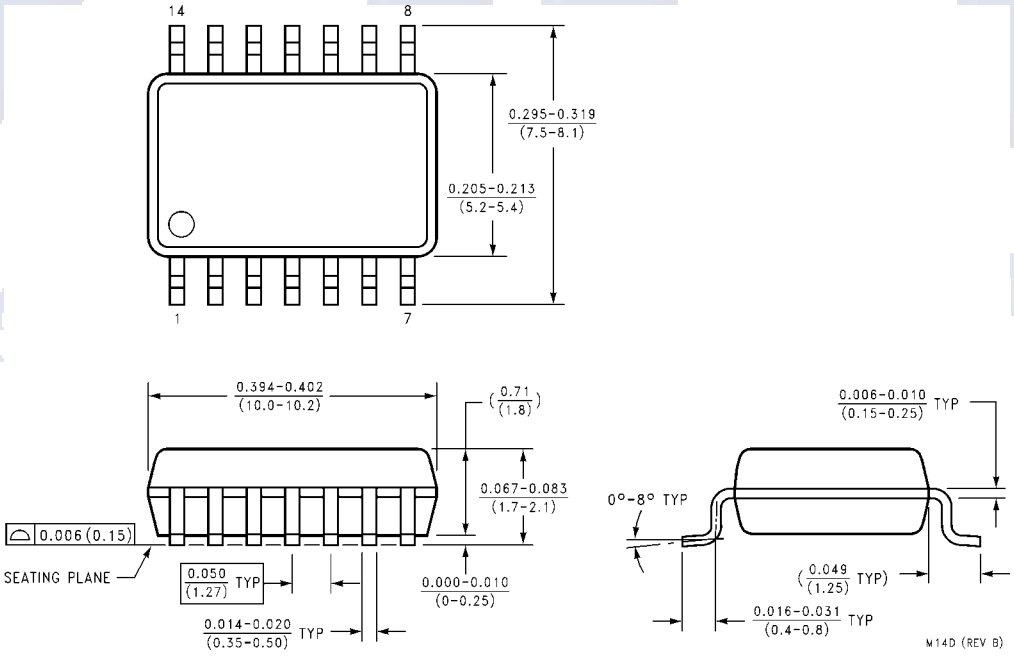
## Physical Dimensions inches (millimeters) unless otherwise noted




**14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-120, 0.150” Narrow Body**
**Package Number M14A**




**14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide**
**Package Number M14D**



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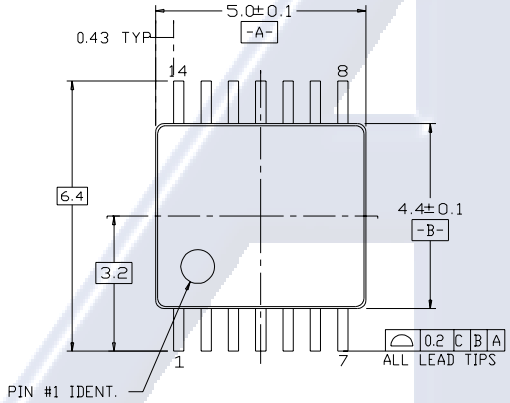
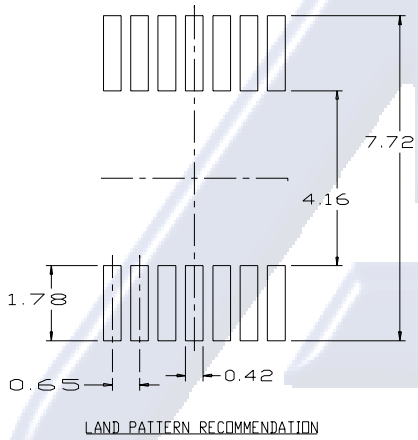
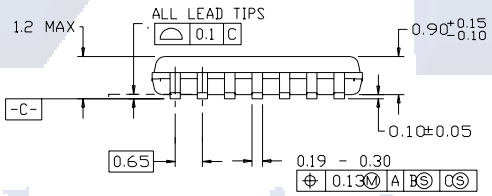
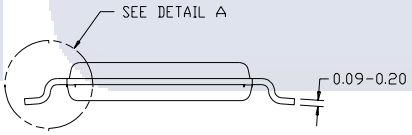
## Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

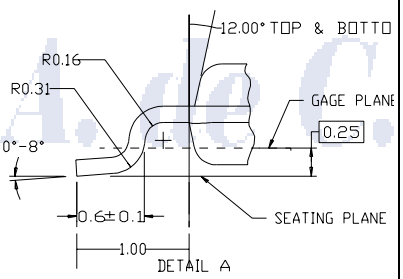
14LD, TSSOP, JEDEC MO-153, 4.4MM WIDE




NOTES:

A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB, REF NOTE 6, DATED 7/93

B. DIMENSIONS ARE IN MILLIMETERS

C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS

**14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide**
**Package Number MTC14**

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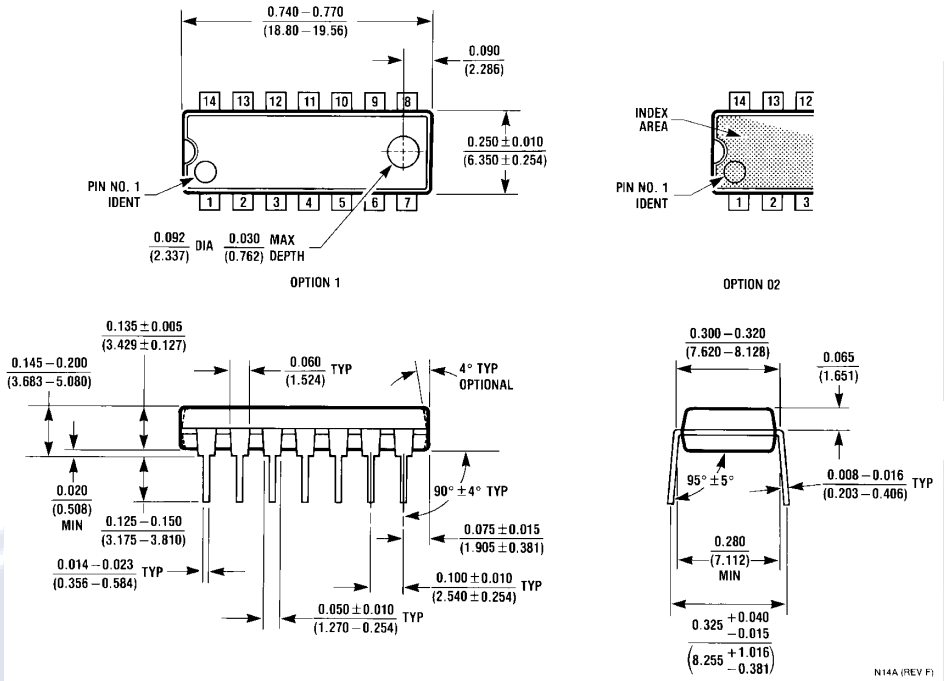
## Physical Dimensions inches (millimeters) unless otherwise noted (Continued)




**14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide**
**Package Number N14A**



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